MICROCHIP

Package Material Content Declaration

Package Description	8-Pad, 6 x 6 x 1.04 mm Body, Lead Pitch 1.27 mm, Leadless Array Package (LAP)		
Lead Finish	Nickel-Gold (Ni-Au)	**Package Code / GPC**	D2B / DMH
J-STD-609 Category	e4	**Termination Base Alloy:**	Laminate

Package Material Declaration

				Homogeneous Material		**Package**	
Material	**Substance**	**CAS #**	**Weight (mg)**	**Percentage**	**ppm**	**Percentage**	**ppm**
Integrated Circuit	Silicon (Si)	7440-21-3	5.017	100.0	1000000	6.71	67096
Sub-Total			**5.017**	**100.0**	**1000000**	**6.71**	**67096**
Die Attach	Silver (Ag)	7440-22-4	0.295	73.9	739000	0.39	3949
	Diester Resin	Proprietary	0.068	17.0	170000	0.09	908
	Acrylate Resin	Proprietary	0.027	6.7	67000	0.04	358
	Polymeric Resin	Proprietary	0.010	2.4	24000	0.01	128
Sub-Total			**0.400**	**100.0**	**1000000**	**0.53**	**5343**
Bond Wire	Gold (Au)	7440-57-5	0.047	100.0	1000000	0.06	623
Sub-Total			**0.047**	**100.0**	**1000000**	**0.06**	**623**
Encapsulation	Silica Fused	60676-86-0	39.293	85.7	857000	52.55	525473
	Epoxy Resin A	Proprietary	1.421	3.1	31000	1.90	19008
	Epoxy Resin B	Proprietary	1.421	3.1	31000	1.90	19008
	Phenol Resin A	Proprietary	1.421	3.1	31000	1.90	19008
	Phenol Resin B	Proprietary	1.421	3.1	31000	1.90	19008
	Metal Hydroxide	Proprietary	0.734	1.6	16000	0.98	9810
	Carbon Black	1333-86-4	0.138	0.3	3000	0.18	1839
Sub-Total			**45.849**	**100.0**	**1000000**	**61.32**	**613153**
Laminate	Copper (Cu)	7440-50-8	9.446	41.7	417000	12.63	126318
	Filament Fiber Glass	65997-17-3	5.097	22.5	225000	6.82	68157
	BT Epoxy Resin	Proprietary	5.097	22.5	225000	6.82	68157
	Inorganic Filler	21645-51-2	3.013	13.3	133000	4.03	40288
Sub-Total			**22.651**	**100.0**	**1000000**	**30.29**	**302920**
Soldermask	Acrylate Resin	Proprietary	0.332	41.0	410000	0.44	4436
	Barium Sulfate	7727-43-7	0.260	32.1	321000	0.35	3473
	Epoxy Resin	Proprietary	0.129	16.0	160000	0.17	1731
	Organic Compounds	Proprietary	0.057	7.1	71000	0.08	768
	Talc	14807-96-6	0.023	2.8	28000	0.03	303
	Silica	7631-86-9	0.006	0.7	7000	0.01	76
	Phthalocyanine Blue	147-14-8	0.002	0.3	3000	0.00	32
Sub-Total			**0.809**	**100.0**	**1000000**	**1.08**	**10819**
Terminal Plating	Nickel (Ni)	7440-02-0	0.003	90.1	901000	0.00	41
	Gold (Au)	7440-57-5	0.000	9.9	99000	0.00	5
Sub-Total			**0.003**	**100.0**	**1000000**	**0.00**	**46**
Total			**74.776**			**100.00**	**1000000**

This semiconductor device and its homogenous materials comply with EU Directives: 2002/95/EC (27 January 2003) & Directive 2011/65/EU (08 June 2011) and 2015/863/EU (31 March 2015) and 2002/53/EC (End-of-Life Vehicles (ELV) without exemption (zero).

Compliance with the above EU Directives has been verified via internal design controls, supplier declarations, and /or analytical test data.

If a chemical substance is absent from the list above, the chemical substance is NOT an intentional ingredient in the semiconductor device and, to the best of Microchip Technology Incorporated's knowledge and belief as of the date of this document, there is no credible reason to believe that the unavoidable impurity concentration of the chemical substance, if any, is not below the threshold of regulatory concern for any regulatory scheme world-wide.

Molding compounds used by Microchip meet the UL94 V0 flammability standard for plastics. You can access the UL iQTM family of databases to obtain a test report at http://ul.com/global/eng/pages/offerings/industries/chemicals/plastics/ .

The protective “tubes” in which the specific product is shipped are made from polyvinyl chloride (PVC) plastic. “Window envelopes” used to hold the packing slip on the outer box and certain “reels” may be made from PVC plastic.

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Assembled package referenced above is EU REACH compliant based on the latest SVHC candidate list of ECHA which can be found at http://echa.europa.eu/web/guest/candidate-list-table.